

**P-2.5 COMMITTEE FOR TANTALUM, NIOBIUM, ALUMINUM CHIP
CAPACITORS
MEETING MINUTES
WEDNESDAY, Oct 8, 2008
SALT LAKE CITY, UT**

I. COMMITTEE ORGANIZATION AND PROCEDURE

1. Membership and attendance

NAME	COMPANY
Jim Connell	Vishay
Mike Lauri	IBM
Jayson Young	Kemet
Harizo Yawary	Cisco
Naqil Samiee	Cisco
Carl E Lindquist	SOC America
Laird Macomber	CDE
Ralph Justus	ECA
Dave Richardson	Vishay

- 2. Approval of agenda**
- 3. Approval of minutes**
- 4. Correspondence**

II. OLD BUSINESS

1. Reports

- a. S-1 Passive Component Steering Committee (Mike Lauri)**

Next meeting in New Orleans, LA.

- b. Government Specifications and standards (DSCC representative)**

No updates presented.

- c. AEC Q200 Subcommittee**

AEC did not accept the Tantalum manufacturers recommended changes for the current draft of Q200. The EIA group will continue to work with the AEC going forward and push for the recommended changes for Tantalum capacitors with regard to the preconditioning and test procedures defined in the Q200 document under revision. Q200 is expected to be finalized by the end of this year.

2. Review of Current Active Specifications

The committee has discussed creating a single document to cover many of the standards for tantalum capacitors including the chip specifications, applications and qualification guidelines. The committee has requested feedback on what standards are being requested by customers and what standards have been purchased recently. Based on the feedback received during this committee meeting, a clear specific need

within the industry with regard to tantalum capacitor standards was not defined.

a. 535BAAC molded Chip Specification

This specification is in need of revision in terms of case size, ESR, dimension, etc.

b. EIA – 809 Applications Guide

1999 was the last revision. This standard may be combined with 535BAAC.

c. EIA- 717 Qualification Spec

A new draft was created but not submitted for approval. This specification may be combined with 535BAAC. The draft will be reviewed once again by the committee before a decision is made.

d. EIA-757 Visual and Mechanical Guide

July, 1998 was last revision. Team members reported that IPC 610 does contain guidelines for assembly and reference to this spec may be advisable since some drawings are in place.

e. Polymer Tantalum Specifications

Feb, 2006. This specification is still current but may be combined with 535BAAC in the future.

3. Review of Current Component Bulletins

a. Shelf life of Tantalum Capacitors

Cisco recommended a spec to cover all products in terms of shelf life. The current recommendations within the component bulletin for shelf life still applies today.

III. NEW BUSINESS

1. List of proposed specification actions

This item was discussed under item "II. Old Business". In addition, an attending user group suggested a qualification standard to cover all tantalum capacitors. The current draft from EIA 717 was presented and discussed. The committee will revisit this draft and consider resuming efforts on this document.

a. Need to write spec description

b. Need to revise spec info on web

c. Specs we need to revise

c. other specs we need to have

d. need to make specs available for purchase

2. Component Bulletins

a. What new CB's do we need? (voltage derating, high temp operation,etc)

No new needs for CB's.

3. Other New Business

Jayson Young was voted in as the new Chairman for the P2.5 Committee replacing Dave Richardson.

IV. ADJOURNMENT